



US00D548193S

(12) **United States Design Patent**  
**Sandgren et al.**

(10) **Patent No.:** **US D548,193 S**

(45) **Date of Patent:** **\*\* Aug. 7, 2007**

(54) **ELECTRONICS MODULE ASSEMBLY**

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(\*\*) Term: **14 Years**

(21) Appl. No.: **29/229,718**

(22) Filed: **May 11, 2005**

(51) **LOC (8) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/162**

(58) **Field of Classification Search** ..... D13/158-168,  
D13/118, 122, 123, 179, 171, 184; D14/371,  
D14/240, 239; D10/46, 49, 96; D24/215;  
361/728, 729, 736, 740, 752, 761; 315/291,  
315/294, 295; 362/559, 225; 700/17-32;  
345/173, 156; 439/761, 341

See application file for complete search history.

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(57) **CLAIM**

The ornamental design of an electronics module assembly, as shown and described.

**DESCRIPTION**

FIG. 1 is a top front left perspective view of an electronics module assembly in accordance with the present invention; FIG. 2 is an exploded view of the electronics module assembly of FIG. 1;

FIG. 3 is a front plan view thereof;

FIG. 4 is a rear plan view thereof;

FIG. 5 is a left side elevational view thereof;

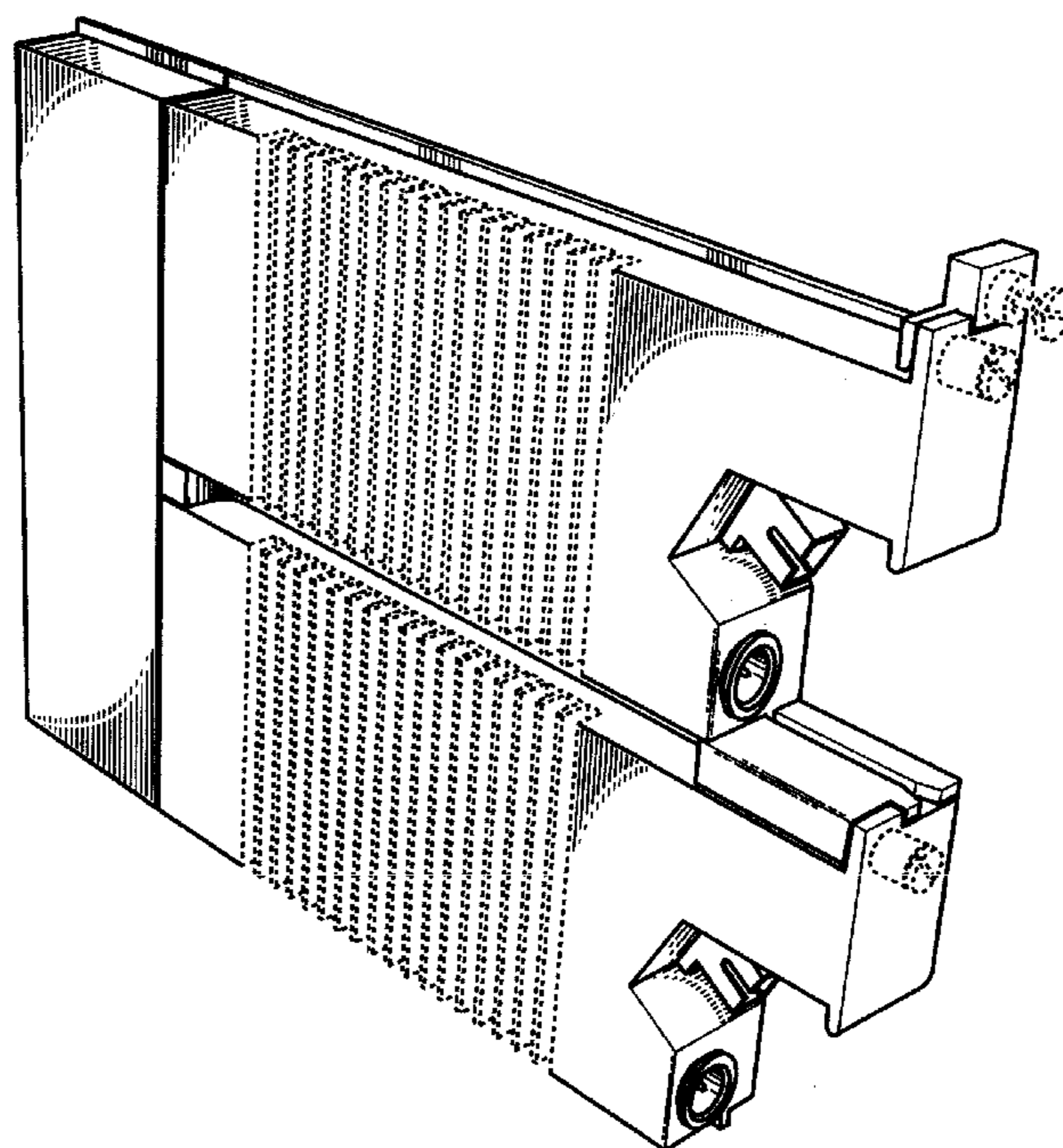
FIG. 6 is a right side elevational view thereof;

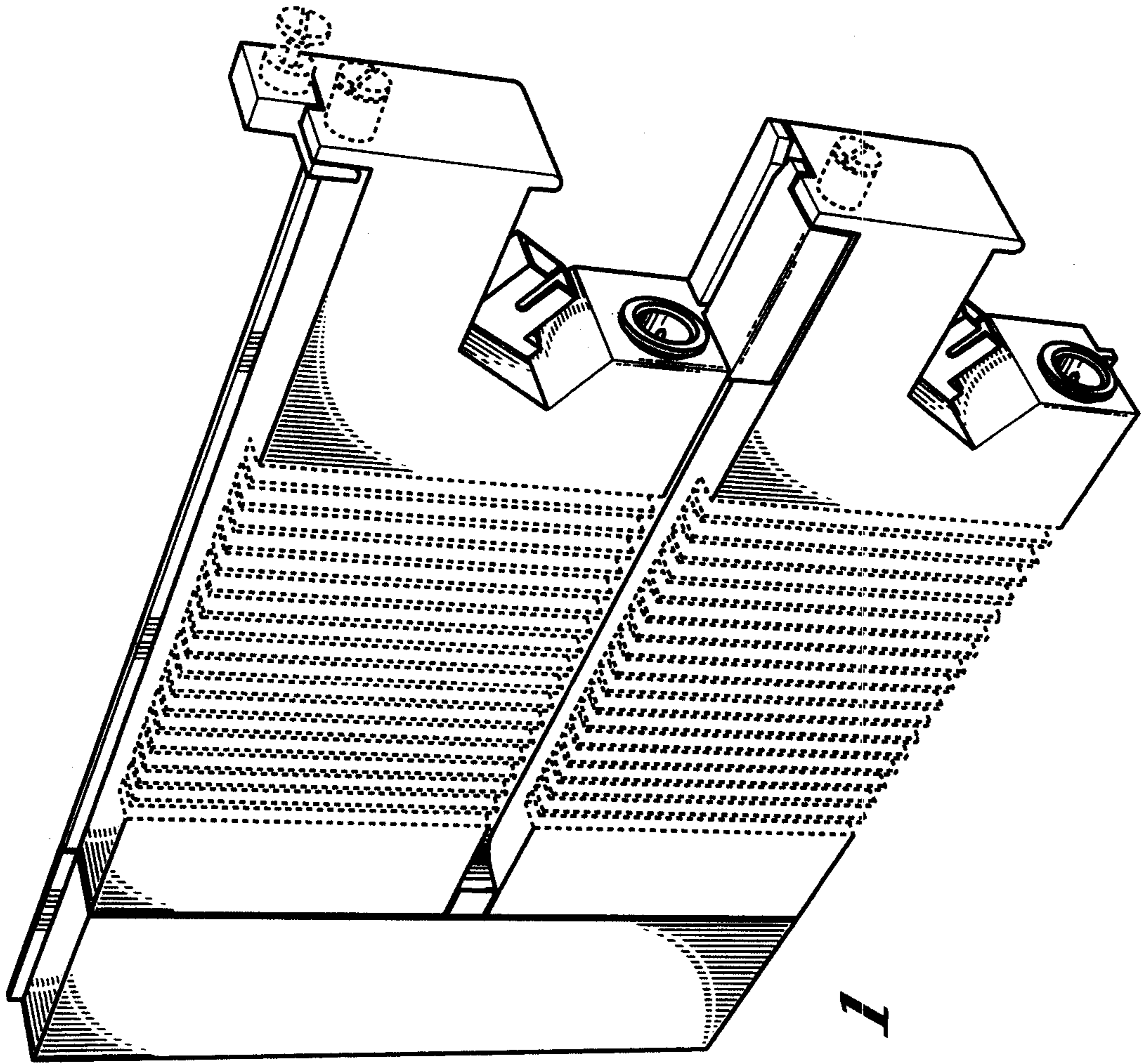
FIG. 7 is a top elevational view; and,

FIG. 8 is a bottom elevational view thereof.

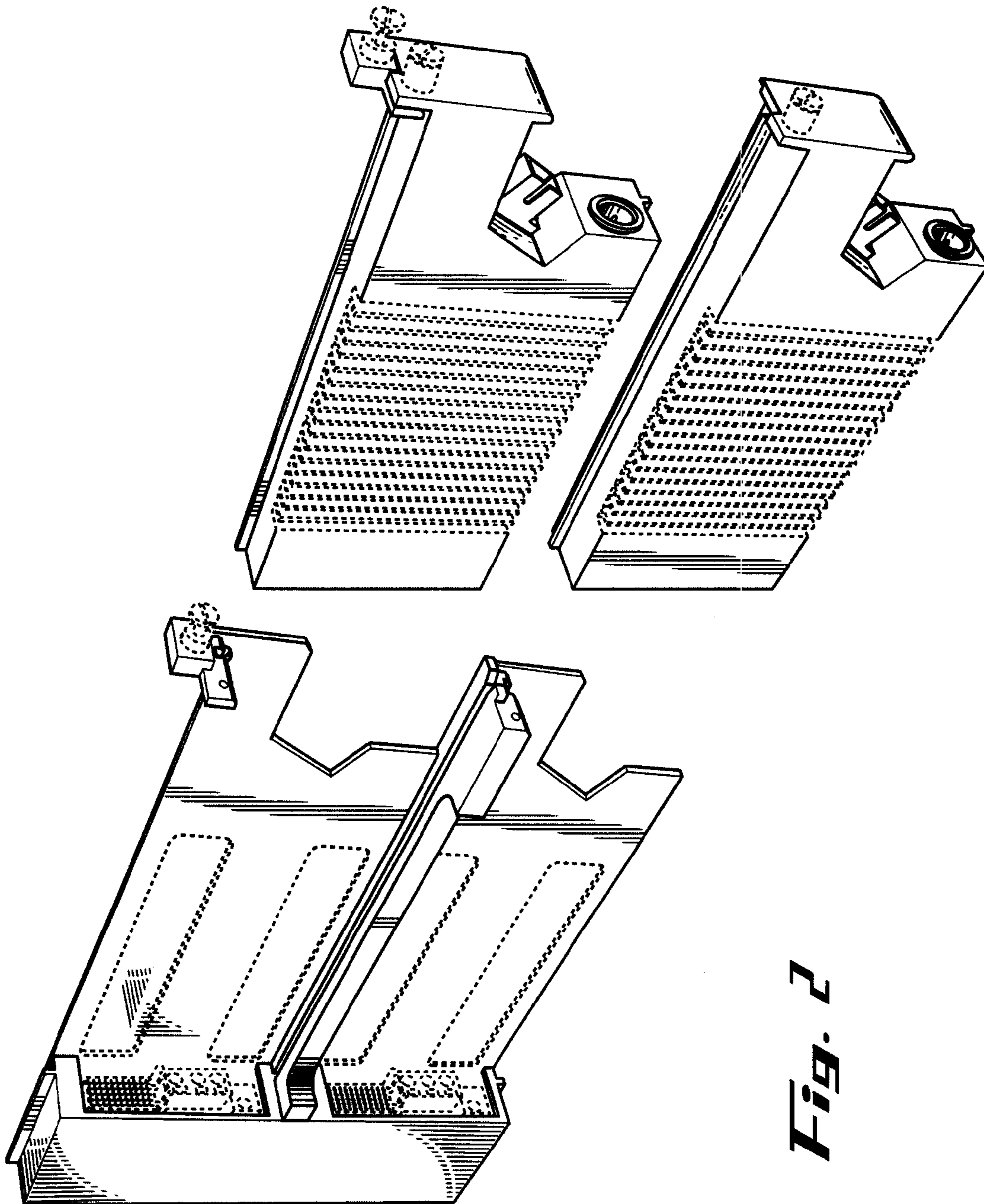
The broken line showing is for illustrative purposes only and forms no part of the claimed design.

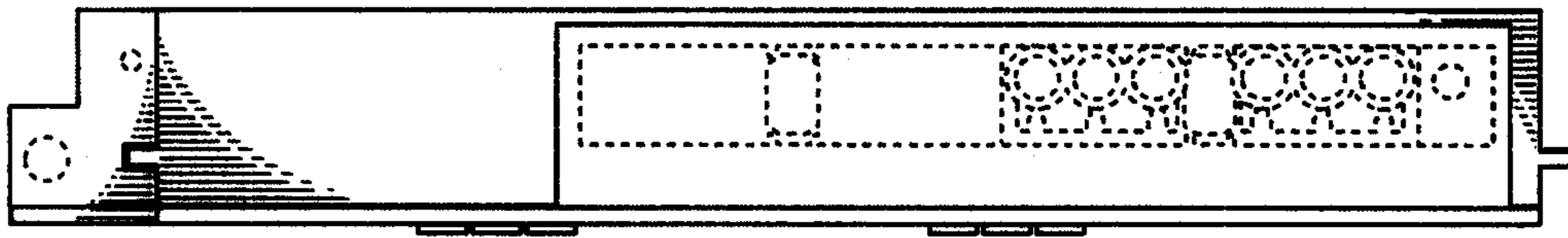
**1 Claim, 6 Drawing Sheets**



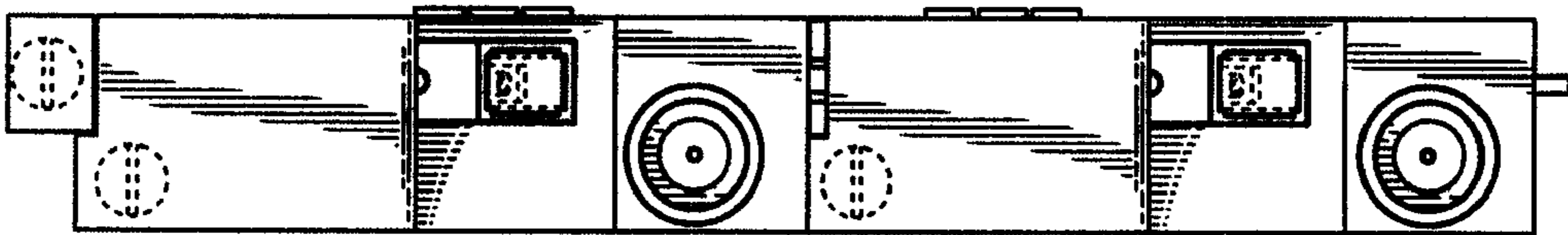


**Fig. 1**

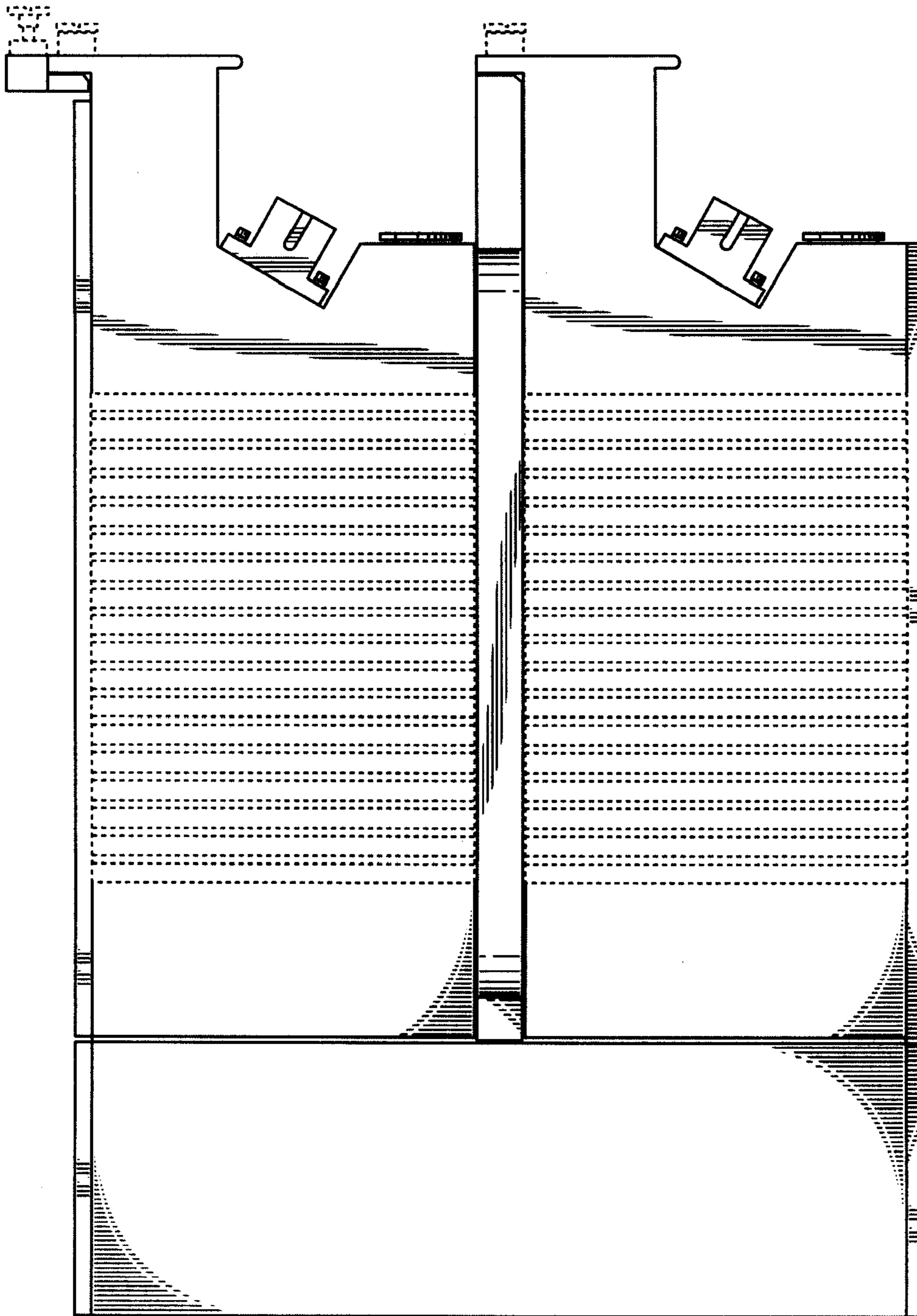




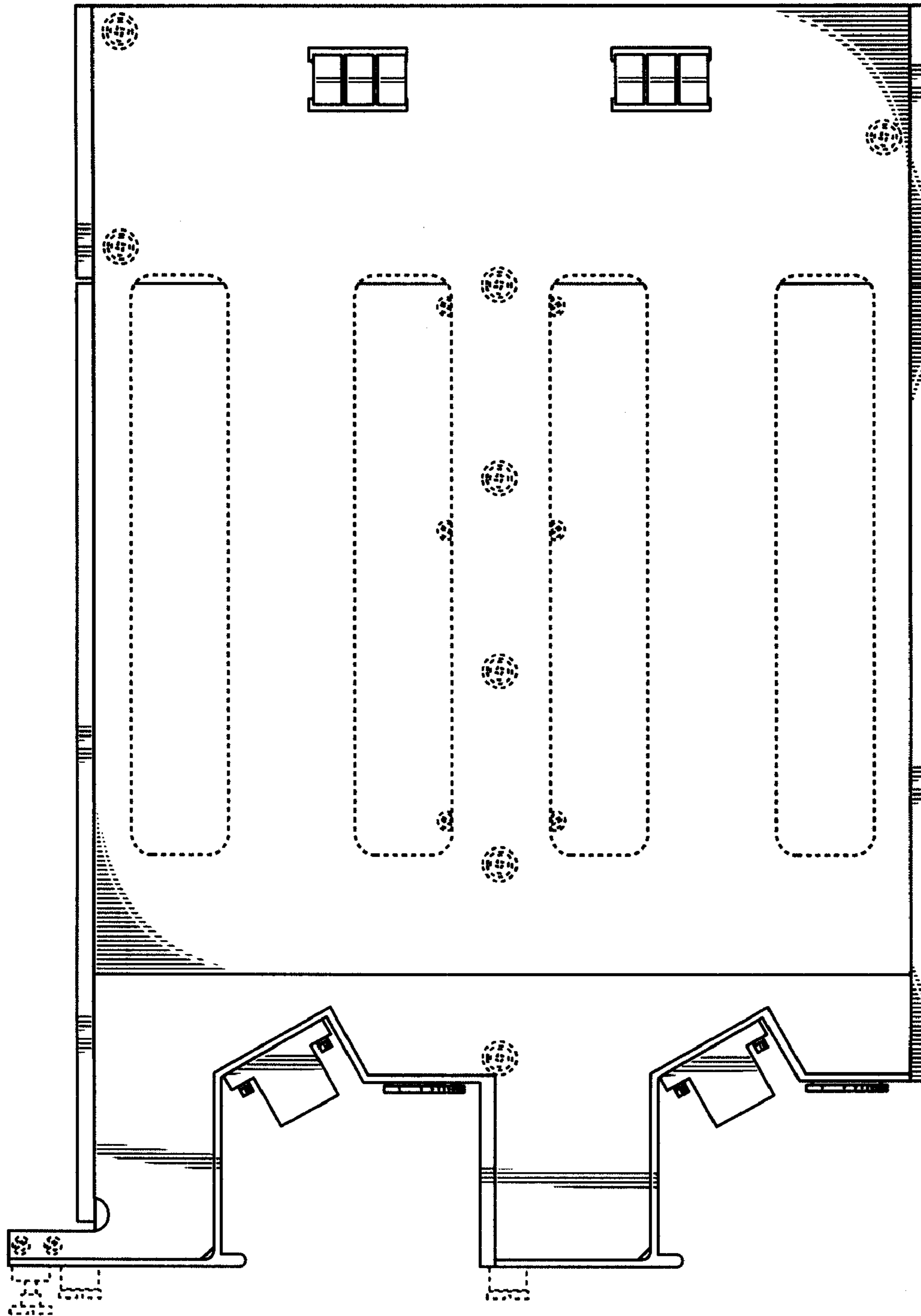
*Fig. 4*



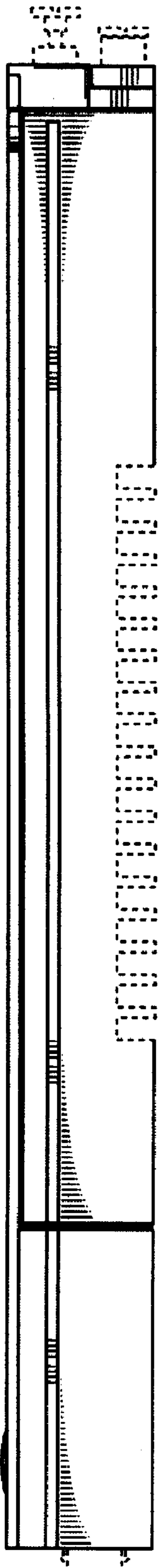
*Fig. 3*



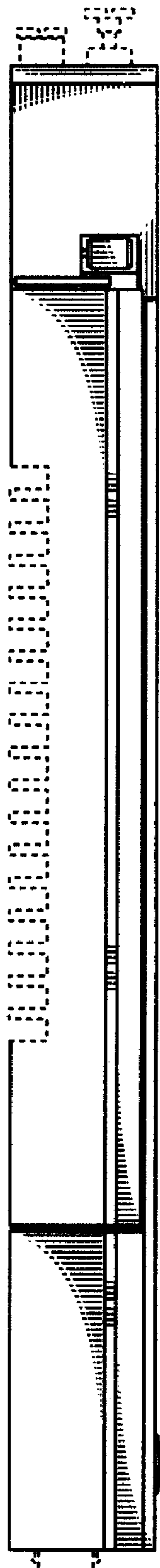
**Fig. 5**



*Fig. 6*



*Fig. 7*



*Fig. 8*